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MOUNTING STRUCTURE FOR A SEMICONDUCTOR IC

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[There are no amendments to this patent.]

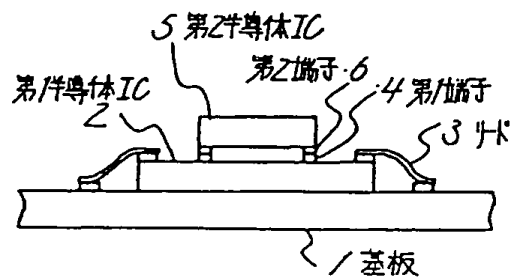
Abstract

Constitution

[The present invention] has a primary semiconductor (IC2), which has multiple terminals (4) at the surface, and a secondary semiconductor (IC5) which has terminals (6) that have shapes that match the terminal (4) of the primary semiconductor (IC2) at the surface, and the terminals (4) of the primary semiconductor (IC2) are directly connected electrically with the terminals (6) of the secondary semiconductor (IC5).

Effect

Many IC pellets can be mounted on a substrate.



Key: 1 Substrate
 2 Primary semiconductor IC
 3 Lead
 4 Primary terminal
 5 Secondary insulator IC
 6 Secondary terminal

Claim

A mounting structure of a semiconductor IC characterized by having a primary semiconductor IC, which has multiple terminals at the surface, and a secondary semiconductor IC, which has terminals that have shapes that match the terminals of said primary semiconductor IC at the surface, with the terminals of the primary semiconductor IC being directly connected electrically with the terminals of the secondary semiconductor IC.

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